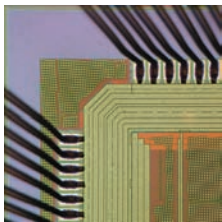
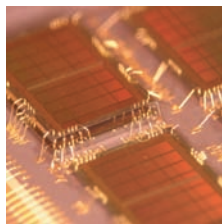
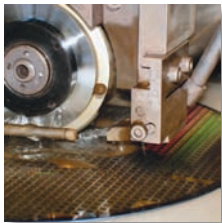




Comprehensive radiation effects test and support

Quick-Turn Prototype IC Assembly

Aeroflex RAD offers the following services: Quick-Turn Prototype IC Assembly in ceramic, etched out plastic, COB and flip chip.



Quick-Turn Prototype IC Assembly Capabilities

- Dicing, Die Visual and Die Attach
 - Wafer Dicing (up to 12inch wafers)
 - Visual Inspection (50-500X)
 - Conductive and non-conductive epoxy die attach
 - Silver Glass and Eutectic die attach
 - Flip Chip
- Wirebond, Encapsulation and Marking
 - Gold and Aluminum Wirebond (to 35µm pitch)
 - Epoxy, Solder, and Glass Frit Lid Seal
 - Dam and Fill (Plastic Encapsulation)
 - Plastic Equivalent Devices
 - COB Glob Top
 - Package Ink Marking or Laser Marking
- Package Options
 - Multi-chip / Stacked Modules, Chip-On-Board (COB) and Custom Substrates
 - Ceramic Packages Including: BGA, PGA, J-Lead, Flat Pack, QFP, Sidebrazed, Cerdip and others
 - Etched Cavity Plastic Packages Including: J-Lead, QFP, SOIC, TSSOP, QFN /MLF and others

Die / Package Thinning and Die Extraction / Repackaging

- Die backside thinning
- Package backside thinning to 35µm ±5µm thickness
- Die extraction and re-bonding
- PC board design

Quality

- DSCC MIL-STD-883/750 Laboratory Suitability
- ISO 9001:2008 Certification

Roadmap

- DSCC QML Cert for MIL-PRF-38535 and MIL-PRF-19500
- AS9100 Certification

